

Amendments to the Specification

Replace paragraph [0077] with the following amended paragraph [0077]:

[0077]

Here, by forming the insulating layer ~~25e~~ 25f on the entire rear surface of the semiconductor chip 25a which includes the projecting part 25e, it is possible to prevent a short circuit occurring between the conductive wires 24d and the rear surface of the semiconductor chip 25a, even in the case where the conductive wires 24d that are connected to the semiconductor chip 24a are high.